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PATENT APPLICATION
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of
Seiichi MIYAZAKI

Application No.: 09/913,334

Docket No.: 110386

Filed: August 13, 2001

For: ETCHANT, ETCHING METHOD AND SEMICONDUCTOR SILICON WAFER

REQUEST FOR CORRECTION OF PALM RECORDS

Director of the U.S. Patent and Trademark Office
Washington, D.C. 20231

Sir:

Attached is a photocopy of the original filing receipt on which errors have been corrected in red. These errors are being brought to the attention of the Patent and Trademark Office so that it may correct its records.

Respectfully submitted,

William P. Berridge
Registration No. 30,024

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WPB:TJP/cmm

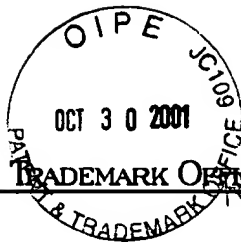
Date: October 30, 2001

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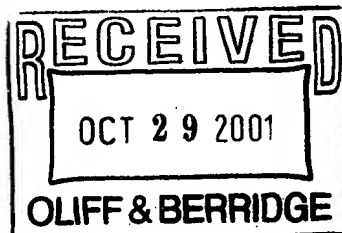
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APPLICATION NUMBER	FILING DATE	GRP ART UNIT	FIL FEE REC'D	ATTY DOCKET NO.	DRGWS	TOT CLAIMS	IND CLAIMS
09/913,334	08/13/2001	2812	1216	110386	2	22	7

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CONFIRMATION NO. 2494

FILING RECEIPT



OC00000006946736

Date Mailed: 10/25/2001

Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Customer Service Center. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

Applicant(s)

Seiichi Miyazaki, Kosyoku-shi, JAPAN;

Domestic Priority data as claimed by applicant

THIS APPLICATION IS A 371 OF PCT/JP00/09185 12/25/2000

Foreign Applications

JAPAN 11-374052 12/28/1999

Projected Publication Date: To Be Determined - pending completion of Security Review

Non-Publication Request: No

Early Publication Request: No

Title

Etchant, etching method and semiconductor silicon wafer

wafer

Preliminary Class

438

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